Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: http://www.renesas.com

April 1st, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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NPN SILICON RF TRANSISTOR NE661M05

NPN SILICON RF TRANSISTOR FOR LOW CURRENT, LOW-NOISE, HIGH-GAIN AMPLIFICATION FLAT-LEAD 4-PIN THIN-TYPE SUPER MINIMOLD (M05)

FEATURES

- Low noise and high gain with low collector current
 NF = 1.2 dB TYP. @ Vce = 2 V, Ic = 2 mA, f = 2 GHz
- Maximum stable power gain: MSG = 22.0 dB TYP. @ VcE = 2 V, Ic = 5 mA, f = 2 GHz
- f_T = 25 GHz technology
- Flat-lead 4-pin thin-type super minimold (M05) package

ORDERING INFORMATION

Part Number	Quantity	Supplying Form
NE661M05	50 pcs (Non reel)	• 8 mm wide embossed taping
NE661M05-T1	3 kpcs/reel	Pin 3 (Collector), Pin 4 (Emitter) face the perforation side of the tape

Remark To order evaluation samples, contact your nearby sales office.

Unit sample quantity is 50 pcs.

ABSOLUTE MAXIMUM RATINGS (TA = +25°C)

Parameter	Symbol	Ratings	Unit
Collector to Base Voltage	Vсво	15	V
Collector to Emitter Voltage	VCEO	3.3	٧
Emitter to Base Voltage	VEBO	1.5	٧
Collector Current	lc	12	mA
Total Power Dissipation	Ptot Note	39	mW
Junction Temperature	Tj	150	°C
Storage Temperature	T _{stg}	-65 to +150	°C

Note Mounted on 1.08 cm² × 1.0 mm (t) glass epoxy PCB

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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ELECTRICAL CHARACTERISTICS (TA = +25°C)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
DC Characteristics						
Collector Cut-off Current	Ісво	Vcb = 5 V, IE = 0 mA	-	-	100	nA
Emitter Cut-off Current	ІЕВО	VEB = 1 V, Ic = 0 mA	-	_	100	nA
DC Current Gain	hfe Note 1	Vce = 2 V, Ic = 5 mA	50	70	100	-
RF Characteristics						
Gain Bandwidth Product	f⊤	Vce = 3 V, Ic = 10 mA, f = 2 GHz	20.0	25.0	-	GHz
Insertion Power Gain	S _{21e} ²	Vce = 2 V, Ic = 5 mA, f = 2 GHz	14.0	17.0	-	dB
Noise Figure	NF	$V_{CE} = 2 \text{ V}, \text{ Ic} = 2 \text{ mA}, \text{ f} = 2 \text{ GHz},$ $Z_{S} = Z_{\text{opt}}$	-	1.2	1.5	dB
Reverse Transfer Capacitance	Cre Note 2	VcB = 2 V, IE = 0 mA, f = 1 MHz	-	0.08	0.12	pF
Maximum Stable Power Gain	MSG Note 3	VcE = 2 V, Ic = 5 mA, f = 2 GHz	0->	22.0	_	dB
Gain 1 dB Compression Output power	Po (1 dB)	Vce = 2 V, Ic = 5 mA, f = 2 GHz	-	5.0	_	dBm
3rd Order Intermodulation Distortion Output Intercept Point	OIP ₃	Vcв = 2 V, Ic = 5 mA, f = 2 GHz		15.0	-	dBm

Notes 1. Pulse measurement: PW \leq 350 μ s, Duty Cycle \leq 2%

2. Collector to base capacitance when the emitter grounded

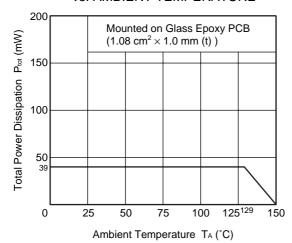
3. MSG =
$$\frac{S_{21}}{S_{12}}$$

hfe CLASSIFICATION

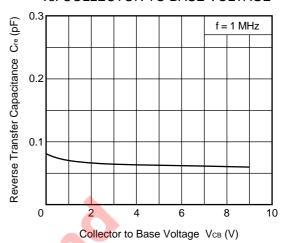
	3. MSG	$S = \left \frac{S_{21}}{S_{12}} \right $	60,9		
	hfe CLASSIFI	CATION	W Or		
	Rank	FB	. 0.		
	Marking	T81			
	hre Value	50 to 100			
600					

★ TYPICAL CHARACTERISTICS (TA = +25°C, unless otherwise specified)

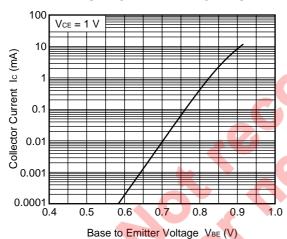
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



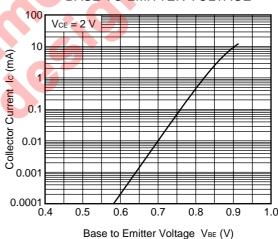
REVERSE TRANSFER CAPACITANCE vs. COLLECTOR TO BASE VOLTAGE



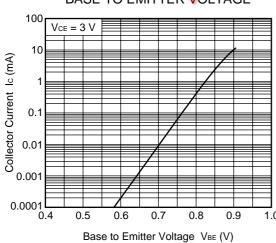
COLLECTOR CURRENT vs. BASE TO EMITTER VOLTAGE



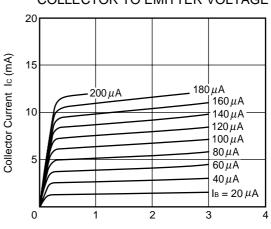
COLLECTOR CURRENT vs.
BASE TO EMITTER VOLTAGE



COLLECTOR CURRENT vs. BASE TO EMITTER VOLTAGE

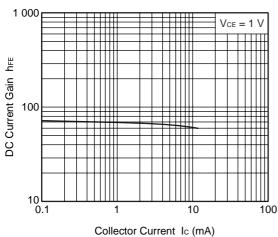


COLLECTOR CURRENT vs.
COLLECTOR TO EMITTER VOLTAGE

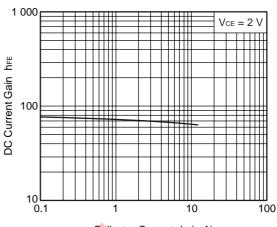


Collector to Emitter Voltage VcE (V)

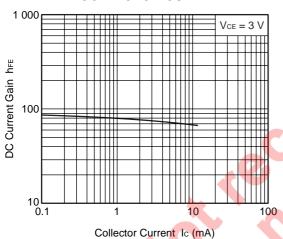
DC CURRENT GAIN vs. COLLECTOR CURRENT



DC CURRENT GAIN vs. COLLECTOR CURRENT



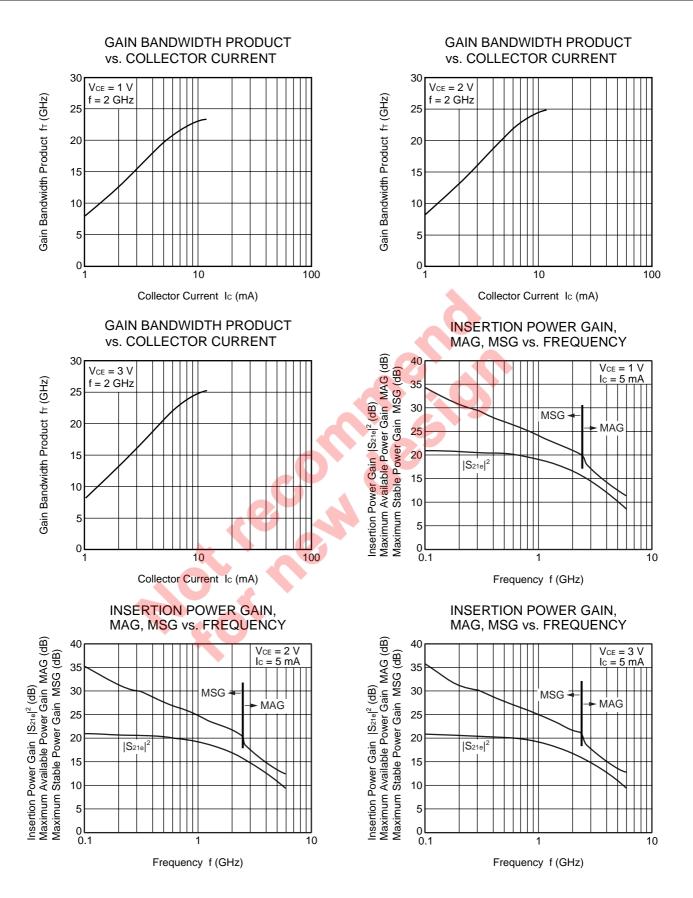
DC CURRENT GAIN vs. COLLECTOR CURRENT



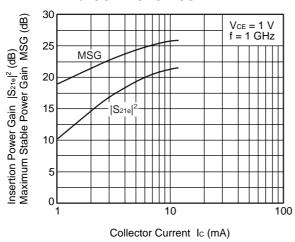
Collector Current Ic (mA)

July 16816

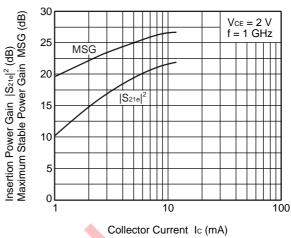




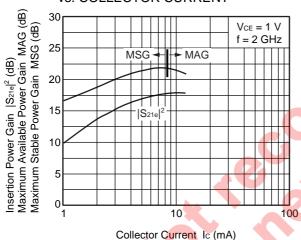
INSERTION POWER GAIN, MSG vs. COLLECTOR CURRENT



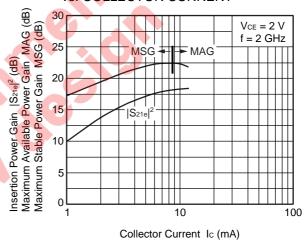
INSERTION POWER GAIN, MSG vs. COLLECTOR CURRENT



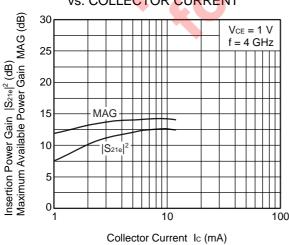
INSERTION POWER GAIN, MAG, MSG vs. COLLECTOR CURRENT



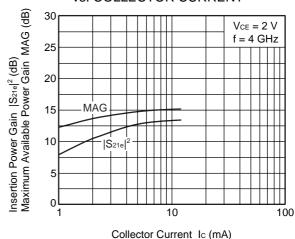
INSERTION POWER GAIN, MAG, MSG vs. COLLECTOR CURRENT



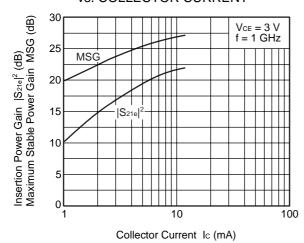
INSERTION POWER GAIN, MAG vs. COLLECTOR CURRENT



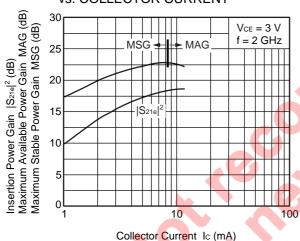
INSERTION POWER GAIN, MAG vs. COLLECTOR CURRENT



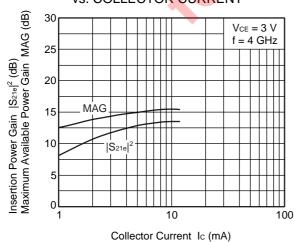
INSERTION POWER GAIN, MSG vs. COLLECTOR CURRENT



INSERTION POWER GAIN, MAG, MSG vs. COLLECTOR CURRENT



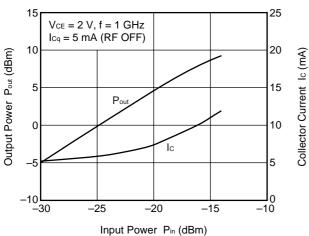
INSERTION POWER GAIN, MAG vs. COLLECTOR CURRENT



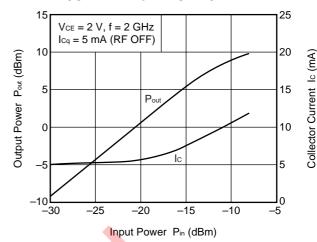
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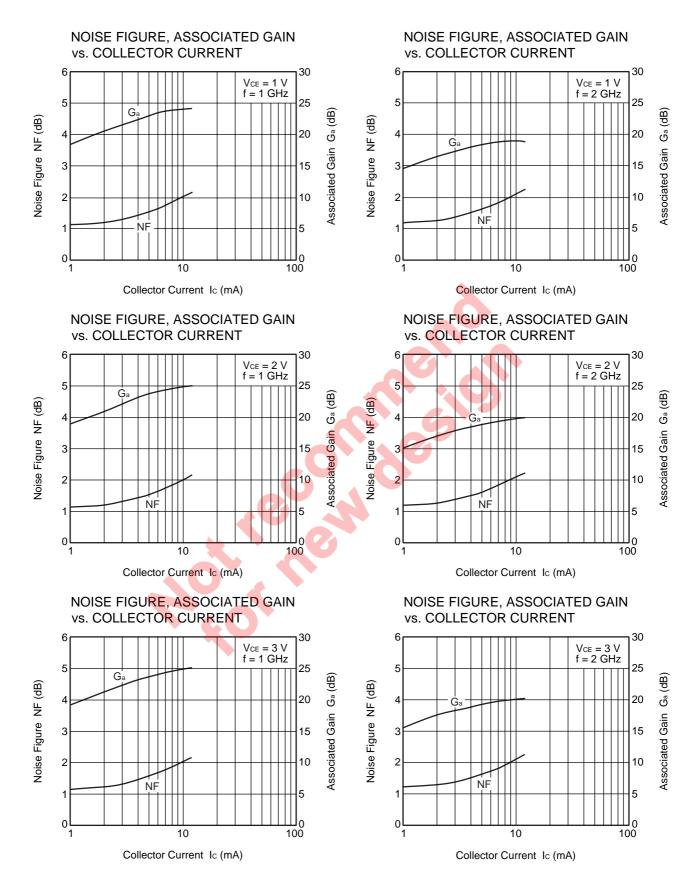
OUTPUT POWER, COLLECTOR CURRENT vs. INPUT POWER



OUTPUT POWER, COLLECTOR CURRENT vs. INPUT POWER



8



Remark The graphs indicate nominal characteristics.

S-PARAMETERS

S-parameters/Noise parameters are provided on the NEC Compound Semiconductor Devices Web site in a form (S2P) that enables direct import to a microwave circuit simulator without keyboard input.

Click here to download S-parameters.

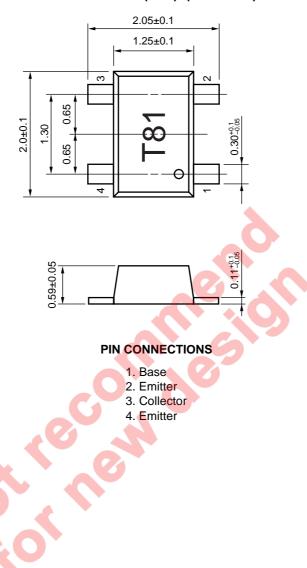
 $[\mathsf{RF} \ \mathsf{and} \ \mathsf{Microwave}] \to [\mathsf{Device} \ \mathsf{Parameters}]$

URL http://www.csd-nec.com/



PACKAGE DIMENSIONS

FLAT-LEAD 4-PIN THIN-TYPE SUPER MINIMOLD (M05) (UNIT: mm)



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